



# **TinyLogic UHS Dual Buffer with 3-STATE Outputs**

#### **NC7WZ126**

#### **Description**

The NC7WZ126 is a Dual Non–Inverting Buffer with independent active HIGH enables for the 3–STATE outputs. The Ultra High Speed device is fabricated with advanced CMOS technology to achieve superior switching performance with high output drive while maintaining low static power dissipation over a broad  $V_{\rm CC}$  operating range. The device is specified to operate over the 1.65 V to 5.5 V  $V_{\rm CC}$  operating range. The inputs and outputs are high impedance when  $V_{\rm CC}$  is 0 V. Inputs tolerate voltages up to 5.5 V independent of  $V_{\rm CC}$  operating range. Outputs tolerate voltages above  $V_{\rm CC}$  when in the 3–STATE condition.

#### **Features**

- Space Saving US8 Surface Mount Package
- MicroPak™ Pb-Free Leadless Package
- Ultra High Speed: t<sub>PD</sub> 2.6 ns Typ. into 50 pF at 5 V V<sub>CC</sub>
- High Output Drive: ±24 mA at 3 V V<sub>CC</sub>
- Broad V<sub>CC</sub> Operating Range: 1.65 V to 5.5 V
- Matches the Performance of LCX when Operated at 3.3 V V<sub>CC</sub>
- Power Down High Impedance Inputs / Outputs
- Overvoltage Tolerant Inputs Facilitate 5 V to 3 V Translation
- Outputs are Overvoltage Tolerant in 3-STATE Mode
- Patented Noise / EMI Reduction Circuitry Implemented
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

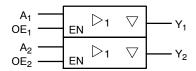


Figure 1. Logic Symbol

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#### MARKING DIAGRAMS



UQFN8 1.6X1.6, 0.5P CASE 523AY





US8 CASE 846AN



T6, WZ26 = Specific Device Code

KK = 2-Digit Lot Run Traceability Code
XY = 2-Digit Date Code Format
Z = Assembly Plant Code
A = Assembly Site
L = Wafer Lot Number
YW = Assembly Start Week

#### **ORDERING INFORMATION**

See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

NOTE: Some of the devices on this data sheet have been **DISCONTINUED**. Please refer to the table on page 6.

#### **Connection Diagrams**

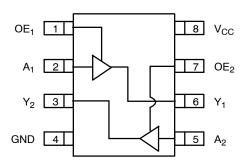


Figure 2. Connection Diagram (Top View)

## OE<sub>1</sub> V<sub>CC</sub> 8 4 GND $A_2$

Figure 3. Pad Assignments for MicroPak (Top Thru View)

#### **PIN DESCRIPTIONS**

Pin Names	Description
OE <sub>n</sub>	Enable Inputs for 3-STATE Outputs
A <sub>n</sub>	Inputs
Y <sub>n</sub>	3-STATE Outputs

#### **FUNCTION TABLE**

Inp	Output	
OE	OE A <sub>n</sub>	
Н	L	L
Н	Н	Н
L	L	Z
L	Н	Z

H = HIGH Logic Level L = LOW Logic Level Z = 3-STATE

#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Min	Max	Unit	
V <sub>CC</sub>	Supply Voltage		-0.5	6.5	V
V <sub>IN</sub>	DC Input Voltage (Note 1)		-0.5	6.5	V
V <sub>OUT</sub>	DC Output Voltage		-0.5	6.5	V
I <sub>IK</sub>	DC Input Diode Current V <sub>IN</sub> < 0 V		-	-50	mA
I <sub>OK</sub>	DC Output Diode Current V <sub>O</sub>	<sub>UT</sub> < 0 V	-	-50	mA
I <sub>OUT</sub>	DC Output Source / Sink Current	-	±50	mA	
I <sub>CC</sub> / I <sub>GND</sub>	DC V <sub>CC</sub> / GND Current	-	±100	mA	
T <sub>STG</sub>	Storage Temperature Range	-65	+150	°C	
TJ	Junction Temperature under Bias	-	+150	°C	
TL	Junction Lead Temperature (Soldering,	-	+260	°C	
P <sub>D</sub>	Power Dissipation in Still Air	US8 MicroPak-8		500 539	mW

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### RECOMMENDED OPERATING CONDITIONS

Symbol		Parameter	Min	Max	Unit
V <sub>CC</sub>	Supply Voltage Operating		1.65	5.5	V
	Supply Voltage Data Reter	ntion	1.5	5.5	
V <sub>IN</sub>	Input Voltage		0	5.5	V
V <sub>OUT</sub>	Output Voltage	Active State	0	V <sub>CC</sub>	V
		3-State	0	5.5	V
T <sub>A</sub>	Operating Temperature		-40	+85	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time V <sub>CC</sub> = 1.8 V ±0.15 V, 2.5 V ±0.2 V		0	20	ns/V
		V <sub>CC</sub> = 3.3 V ±0.3 V	0	10	1
		V <sub>CC</sub> = 5.0 V ±0.5 V	0	5	1
$\theta_{\sf JA}$	Thermal Resistance	US8 MicroPak-8	- -	250 232	°C/W

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

2. Unused inputs must be held HIGH or LOW. They may not float.

<sup>1.</sup> The input and output negative voltage ratings may be exceeded is the input and output diode current ratings are observed.

#### DC ELECTICAL CHARACTERISTICS

					T <sub>A</sub> = +25°C			T <sub>A</sub> = -40 to +85°C		
Symbol	Parameter	Cond	litions	V <sub>CC</sub> (V)	Min	Тур	Max	Min	Max	Unit
$V_{IH}$	HIGH Level Input			1.65 to 1.95	0.65 V <sub>CC</sub>	_	-	0.65 V <sub>CC</sub>	_	V
	Voltage			2.3 to 5.5	0.7 V <sub>CC</sub>	_	-	0.7 V <sub>CC</sub>	_	
$V_{IL}$	LOW Level Input			1.65 to 1.95	-	_	0.35 V <sub>CC</sub>	-	0.35 V <sub>CC</sub>	V
	Voltage			2.3 to 5.5	-	_	0.3 V <sub>CC</sub>	-	0.3 V <sub>CC</sub>	
V <sub>OH</sub>	HIGH Level Output	$V_{IN} = V_{IH}$ or	I <sub>OH</sub> = -100 μA	1.65	1.55	1.65	-	1.55	=	V
	Voltage	V <sub>IL</sub>		2.3	2.2	2.3	-	2.2	-	
				3.0	2.9	3.0	-	2.9	=	
				4.5	4.4	4.5	-	4.4	-	
		$V_{IN} = V_{IH}$ or	$I_{OH} = -4 \text{ mA}$	1.65	1.29	1.52	-	1.29	-	
		V <sub>IL</sub>	$I_{OH} = -8 \text{ mA}$	2.3	1.9	2.15	-	1.9	-	
			I <sub>OH</sub> = -16 mA	3.0	2.4	2.80	-	2.4	-	
			$I_{OH} = -24 \text{ mA}$	3.0	2.3	2.68	-	2.3	_	
			$I_{OH} = -32 \text{ mA}$	4.5	3.8	4.20	-	3.8	_	
$V_{OL}$	L LOW Level Output	LOW Level Output $V_{IN} = V_{II}$ Voltage $V_{IL}$			0.10	_	0.10	V		
	Voltage	V L		2.3	-	0.0	0.10	-	0.10	
				3.0	-	0.0	0.10	-	0.10	
				4.5	-	0.0	0.10	_	0.10	
		V <sub>IN</sub> = V <sub>IH</sub> or	I <sub>OL</sub> = 4 mA	1.65	-	0.08	0.24	_	0.24	
		V <sub>IL</sub>	I <sub>OL</sub> = 8 mA	2.3	-	0.10	0.3	_	0.3	
			I <sub>OL</sub> = 16 mA	3.0	-	0.15	0.4	_	0.4	
			I <sub>OL</sub> = 24 mA	3.0	-	0.22	0.55	-	0.55	
			I <sub>OL</sub> = 32 mA	4.5	-	0.22	0.55	-	0.55	
I <sub>IN</sub>	Input Leakage Current	V <sub>IN</sub> = 5.5 V, G	ND	1.65 to 5.5	-	-	±0.1	-	±1	μΑ
l <sub>OZ</sub>	3-STATE Output Leakage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $0 \le V_{OUT} \le 5.5 \text{ V}$		1.65 to 5.5	-	-	±0.5	-	±5	μΑ
I <sub>OFF</sub>	Power Off Leakage Current	V <sub>IN</sub> or V <sub>OUT</sub> =	5.5 V	0.0	_	-	1	_	10	μΑ
I <sub>CC</sub>	Quiescent Supply Current	V <sub>IN</sub> = 5.5 V, GI	ND	1.65 to 5.5	-	_	1	-	10	μΑ

#### **NOISE CHARACTERISTICS**

				T <sub>A</sub> = +25°C		
Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	Тур	Max	Unit
V <sub>OLP</sub> (Note 3)	Quiet Output Maximum Dynamic V <sub>OL</sub>	C <sub>L</sub> = 50 pF	5.0	-	1.0	V
V <sub>OLV</sub> (Note 3)	Quiet Output Minimum Dynamic V <sub>OL</sub>	C <sub>L</sub> = 50 pF	5.0	-	1.0	V
V <sub>OHV</sub> (Note 3)	Quiet Output Minimum Dynamic V <sub>OH</sub>	C <sub>L</sub> = 50 pF	5.0	-	4.0	V
V <sub>IHD</sub> (Note 3)	Minimum HIGH Level Dynamic Input Voltage	C <sub>L</sub> = 50 pF	5.0	-	3.5	V
V <sub>ILD</sub> (Note 3)	Maximum LOW Level Dynamic Input Voltage	C <sub>L</sub> = 50 pF	5.0	_	1.5	٧

<sup>3.</sup> Parameter guaranteed by design.

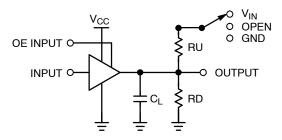


#### **AC ELECTRICAL CHARACTERISTICS**

					T <sub>A</sub> = +25°C	;	T <sub>A</sub> = -40	to +85°C				
Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	Min	Тур	Max	Min	Max	Unit			
t <sub>PLH</sub>	Propagation Delay C <sub>L</sub> = 15 pF		1.8 ±0.15	-	-	12.0	-	13.0	ns			
t <sub>PHL</sub>	A <sub>n</sub> to Yn (Figure 4, 6)	$RD = 1 M\Omega$ $S_1 = OPEN$	2.5 ±0.2	-	-	7.5	-	8.0				
			3.3 ±0.3	-	-	5.2	-	5.5				
			5.0 ±0.5	_	-	4.5	-	4.8				
		$C_L = 50 \text{ pF},$ RD = 500 $\Omega$	3.3 ±0.3	-	-	5.7	-	6.0				
		$S_1 = OPEN$	5.0 ±0.5	-	-	5.0	-	5.3				
<sup>t</sup> oslh	Output to Output Skew		3.3 ±0.3	_	-	1.0	-	1.0	ns			
t <sub>OSHL</sub>	(Note 4) (Figure 4, 6)		5.0 ±0.5	_	-	0.8	-	0.8				
t <sub>PZL</sub>	(Figure 4, 6) $RD,F$ $S_1 =$		1.8 ±0.15	_	-	14.0	-	15.0	ns			
t <sub>PZH</sub>		$S_1 = GND \text{ for } t_{PZH}$ $S_1 = V_1 \text{ for } t_{PZL}$	$S_1 = V_I$ for $t_{PZL}$	$S_1 = GND \text{ for } t_{PZH}$ $S_1 = V_I \text{ for } t_{PZL}$	$S_1 = GND \text{ for } t_{PZH}$ $S_1 = V_1 \text{ for } t_{PZL}$	$S_1 = GND \text{ for } t_{PZH}$ $S_1 = V_I \text{ for } t_{PZL}$	2.5 ±0.2	_	-	8.5	-	9.0
							$S_1 = V_I \text{ for } t_{PZL}$ $V_I = 2 \times V_{CC}$	$S_1 = V_I \text{ for } t_{PZL}$ $V_I = 2 \times V_{CC}$	S <sub>1</sub> = V <sub>I</sub> for t <sub>PZL</sub> V <sub>I</sub> = 2 x V <sub>CC</sub>	3.3 ±0.3	-	-
			5.0 ±0.5	-	-	5.5	-	5.8				
t <sub>PLZ</sub>	Output Disable Time	C <sub>L</sub> = 50 pF	1.8 ±0.15	-	-	12.0	-	13.0	ns			
t <sub>PHZ</sub>	(Figure 4, 6)	RD,RU = 500 $\Omega$ S <sub>1</sub> = GND for t <sub>PZH</sub>	2.5 ±0.2	-	-	8.0	-	8.5				
		$S_1 = V_I \text{ for } t_{PZL}$ $V_I = 2 \times V_{CC}$	3.3 ±0.3	_	-	5.7	-	6.0				
			5.0 ±0.5	_	-	4.7	-	5.0				
C <sub>IN</sub>	Input Capacitance		0	_	2.5	_	-	-	pF			
C <sub>OUT</sub>	Output Capacitance		5.0	-	4	_	-	-	pF			
C <sub>PD</sub>	Power Dissipation Capacitance (Figure 5)	(Note 5)	3.3	_	10	_	-	-	pF			
	Capacitance (Figure 5)		5.0	-	12	_	-	-				

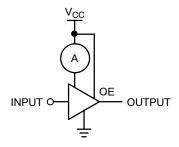
 <sup>4.</sup> Parameter guaranteed by design. t<sub>OSLH</sub> = |t<sub>PLHmax</sub> - t<sub>PLHmin</sub>|; t<sub>OSHL</sub> = |t<sub>PHLmax</sub> - t<sub>PHLmin</sub>|.
 5. C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I<sub>CCD</sub>) at no output loading and operating at 50% duty cycle. (see Figure 5) C<sub>PD</sub> is related to I<sub>CCD</sub> dynamic operating current by the expression:  $I_{CCD} = (CPD) (V_{CC}) (f_{IN}) + (I_{CC}static).$ 

#### **AC Loading and Waveforms**



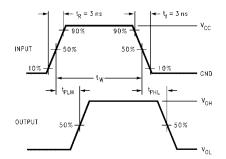
 $C_L$  includes load and stray capacitance Input PRR = 1.0 MHz;  $t_W$  = 500 ns

Figure 4. AC Test Circuit



Input = AC Waveform;  $t_r = t_f = 1.8 \text{ ns}$ ; PRR = 10 MHz; Duty Cycle = 50%.

Figure 5. I<sub>CCD</sub> Test Circuit



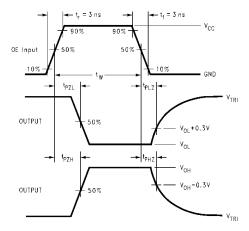


Figure 6. AC Waveforms

#### **ORDERING INFORMATION**

Order Number	Top Mark	Package	Shipping <sup>†</sup>
NC7WZ126K8X	WZ26	8-Lead US8, JEDEC MO-187, Variation CA 3.1 mm Wide	3000 / Tape & Reel
NC7WZ126L8X	T6	8-Lead MicroPak, 1.6 mm Wide (Pb-Free)	5000 / Tape & Reel

#### **DISCONTINUED** (Note 7)

NC7WZ126L8X-L22185	T6	8-Lead MicroPak, 1.6 mm Wide	5000 / Tape & Reel
		(Pb-Free)	-

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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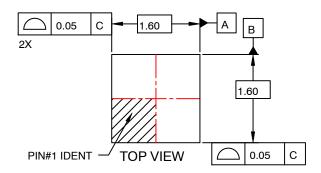
<sup>6.</sup> Pb-Free package per JEDEC J-STD-020B.

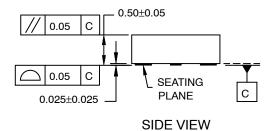
<sup>7.</sup> **DISCONTINUED:** This device is not recommended for new design. Please contact your **onsemi** representative for information. The most current information on this device may be available on <a href="https://www.onsemi.com">www.onsemi.com</a>.

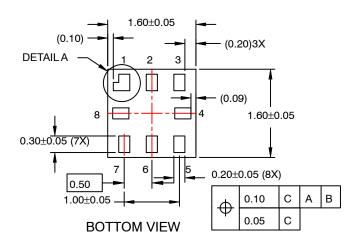


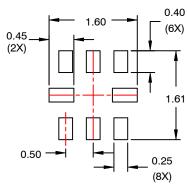
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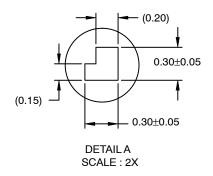




RECOMMENDED LAND PATTERN

#### NOTES:

- A. PACKAGE CONFORMS TO JEDEC MO-255 VARIATION UAAD.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.



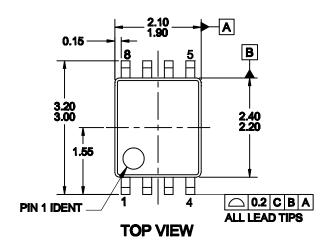
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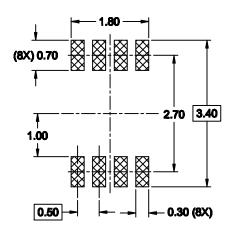
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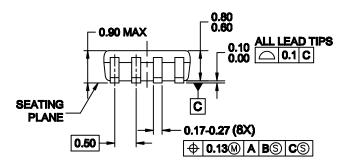
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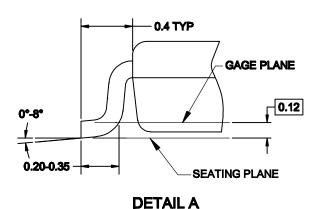
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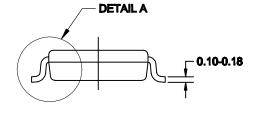


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- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1994.

#### SIDE VIEW





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